



## Revision History

Date	Notes
April 12, 2011	Initial release.
July 4, 2011	Lot of updates and fixes.
September 1, 2011	Remove bump related spec and add some minor modifications.
October 12, 2011	Add pad sizes and die layout details.
November 23, 2011	Correct types for bits 0 & 1 in register 0X05.
January 25, 2012	Add solder bump specification.
February 27, 2012	Add typical values for lcc1 and lcc2. Revised solder bump specification.
March 12, 2013	Administrative error fix.
January 22, 2018	Changed to IDT Branding.

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